

- 1 (Previously Presented) An electronic component comprising:
a substrate; and
an airbridge located over the substrate and having at least a first layer and a second layer, wherein a first portion of the second layer is over the first layer, wherein:
a gap exists between a portion of the airbridge and the substrate; and
a thickness of the second layer is less than a combined thickness of the first layer and the gap;
the airbridge is electrically conductive; and
the first layer of the airbridge is less resistive than the second layer of the airbridge.
2. (Original) The electronic component of claim 1 wherein:
the second layer is a passivation layer.
3. (Original) The electronic component of claim 1 wherein:
the second layer is harder than the first layer.
4. (Canceled)
5. (Original) The electronic component of claim 4 wherein:
the thickness of the second layer is less than fifty percent of the combined thickness of the first layer and the gap.
6. (Previously Presented) The electronic component of claim 1 wherein:
a second portion of the second layer is located underneath an edge of the first layer.
7. (Original) The electronic component of claim 1 wherein:
the second layer is absent underneath a center portion of a width of the airbridge.
8. (Original) The electronic component of claim 1 wherein:
a gap exists underneath a portion of the airbridge; and
the gap is unsealed underneath the portion of the airbridge.

9. (Original) The electronic component of claim 1 wherein:
the second layer of the airbridge has a compressive stress level of approximately
0 to 200 MegaPascals.

10. (Original) The electronic component of claim 1 wherein:
the airbridge further comprises:

a third layer underneath the first layer; and
the third layer is more resistive than the first layer.

11. (Original) The electronic component of claim 10 wherein:
the second layer is more resistive than the third layer.

12. (Original) The electronic component of claim 1 wherein:
the second layer of the airbridge is electrically conductive.

13. (Original) The electronic component of claim 1 wherein:
the second layer of the airbridge is electrically insulative.

14. (Currently Amended) A semiconductor component comprising:
a semiconductor substrate;
a semiconductor device supported by the semiconductor substrate;
a first electrically insulative layer overlying the semiconductor substrate and the
semiconductor device; and

an airbridge located over the semiconductor substrate, located over the first
electrically insulative layer, and electrically coupled to the semiconductor device,

wherein:

a gap exists between a portion of the airbridge and the first electrically
insulative layer;

the airbridge has a first electrically conductive layer; and

the airbridge has a second electrically insulative layer overlying the first
electrically conductive layer; and

the second electrically insulative layer is a passivation layer harder than the first
electrically conductive layer; and

the airbridge further comprises:

an electrically conductive barrier layer located underneath the first electrically conductive layer and more resistive than the first electrically conductive layer.

15. (Canceled)

16. (Currently Amended) The semiconductor component of claim ~~15~~ 14 wherein:

a thickness of the second electrically insulative layer is less than fifty percent of a combined thickness of the electrically conductive barrier layer, the first electrically conductive layer, and the gap.

DOCKET NO. SC11152ZP

17. (Currently Amended) The semiconductor component of claim ~~15~~ 14 wherein:
the second electrically insulative layer is devoid of sealing the gap underneath the portion
of the airbridge.

18. – 33. Canceled

34. (Currently Amended) A method of manufacturing an electronic component comprising:

providing a substrate;

forming an electrically insulative layer over the substrate;

forming a first layer over the first electrically insulative layer to form a first portion of an airbridge;

forming a first portion of a second layer over the first layer to form a second portion of the airbridge over the substrate;

forming a gap between the airbridge and the electrically insulative layer; and

designing the airbridge to have a design width,

wherein:

the airbridge is electrically conductive;

the first layer of the airbridge is less resistive than the second layer of the airbridge; and

~~The method of claim 20 further comprising:~~

forming the first layer further comprises:

forming the first layer to have a first layer width greater than the design width; and

forming the second layer further comprises:

forming a second portion of the second layer underneath edges of the first layer; and

keeping the second layer absent underneath a central portion of the first layer, the central portion of the first layer having the design width.